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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Kayvan Sadra, et al.

Serial No.: 10/694,237

Filed: 10/27/03

For: Application of Different Isolation Schemes for Logic and Embedded Memory

TI-35961

Examiner: Laura M. Schillinger

Art Unit: 2813

**NOTICE OF APPEAL FROM THE PRIMARY EXAMINER TO THE BOARD OF APPEALS**

25

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the above correspondence is being transmitted by facsimile to the U.S. Patent and Trademark Office at 571-273-8300 on the date shown below:

Karen Vertz  
Karen Vertz

10-26-05  
Date

Applicant hereby appeals claims 1-12 to the Board of Appeals from the decision dated July 27, 2005 of the Primary Examiner finally rejecting claims 1-12.

The item(s) checked below are appropriate:

1. ☐ An extension of time to respond to the final rejection  
☐ was granted on \_\_\_\_\_.  
☐ is requested for \_\_\_\_\_ month(s).
2. ☐ A timely response to the final rejection has been filed, as provided in 841 O.G. 1411.
3. ☒ Fee \$500.00:  
☐ Not required (Fee paid in prior appeal)  
☒ The Commissioner of Patents is hereby authorized to charge any fees which may be required, or credit any overpayment to Deposit Account No. 20-0668 of Texas Instruments Incorporated.

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Signature [Rule 191(b)]

Post Office Address (to which correspondence is to be sent)  
Texas Instruments Incorporated  
P.O. Box 655474, MS 3999  
Dallas, TX 75265  
(972) 917-4167

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10/28/2005 BABRAHA1 00000030 200668 10694237  
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Applicant: Kayvan Sadra, et al.

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For: Application of Different Isolation Schemes for Logic and  
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**CERTIFICATION OF FACSIMILE TRANSMISSION**

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<input type="checkbox"/> <b>CONTINUATION APP'N</b>	<input type="checkbox"/> <b>ELECTION</b>
<input type="checkbox"/> <b>DIVISIONAL APP'N</b>	
<b>NAME OF INVENTOR(S):</b> Kayvan Sadra, et al.	
<b>TITLE OF INVENTION:</b> Application of Different Isolation Schemes for Logic and Embedded Memory	
<b>TI FILE NO.:</b> TI-35961	<b>DEPOSIT ACCT. NO.:</b> 20-0668
<b>FAXED:</b> 10-26-05 <b>DUE:</b> 10-27-05 <b>ATTY/SECY:</b> RAK/kv	
<b>RECEIPT DATE &amp; SERIAL NO.:</b> Serial No.: 10/694,237 Filing Date: 10/27/03	

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